Product Change Notification

Change Notification #: **116072 - 00**

Change Title: **Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N,**

Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N,

Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH,

Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS,

Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS

PCN 116072-00, Product Design, Label, Firmware Updates, Regulatory Label Updates, Chassis Bracket and Gasket Updates

Date of Publication: **February 13, 2018**

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 16, 2018

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	**Product Description**
100SWD06B1N	Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N
100SWD24B1N	Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N
100SWDMGTSH	Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH
100SWD06CHS	Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS
100SWD24CHS	Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS

Overview of Changes:

Change 1: The switch firmware version shall be updated from 10.2 to 10.5.1.

Change 2: The regulatory label shall be updated to reflect multiple certification changes.

Change 3: There are minor mechanical changes that will enable the switch chassis to accommodate a full installation of the 48-port leaf modules.

Product Change Details:

Change 1: The switch firmware version shall be updated from 10.2.0.0.152/154 to 10.5.0.0.143/10.5.1.0.2, as shown in **Table 1** below. See 10.5.1 Release Notes J80201 for further details.

Table 1. Firmware Update

DESCRIPTION	**FROM**		**TO**	
	FILE NAME	**VERSION**	**FILE NAME**	**VERSION**
Internally-Managed FW	STL1.q7.10.2.0.0.154.spkg	10.2.0.0.154	STL1.q7.10.5.1.0.2.spkg	10.5.1.0.2
Externally-Managed FW	Intel_PRREdge_V1_firmware. 10.2.0.0.152.emfw	10.2.0.0.152	Intel_PRREdge_V1_firmware.10.5.0.0.143.emfw	10.5.0.0.143

Change 2: An updated regulatory certification was acquired for BSMI (Taiwan) showing compliance with the new Taiwan RoHS requirement. In addition, compliance with the new Ukrainian RoHS requirement was documented. The right side regulatory label shall be updated to reflect compliance with these new RoHS requirements, as well as the new ANATEL certification to enable shipments to Brazil.

The regulatory label updates for 100SWD06B1N and 100SWD06CHS are shown in **Figure 1** and **Figure 2** below.

Figure 1. 100SWD06 Regulatory Label, Before

Figure 2. 100SWD06 Regulatory Label, After

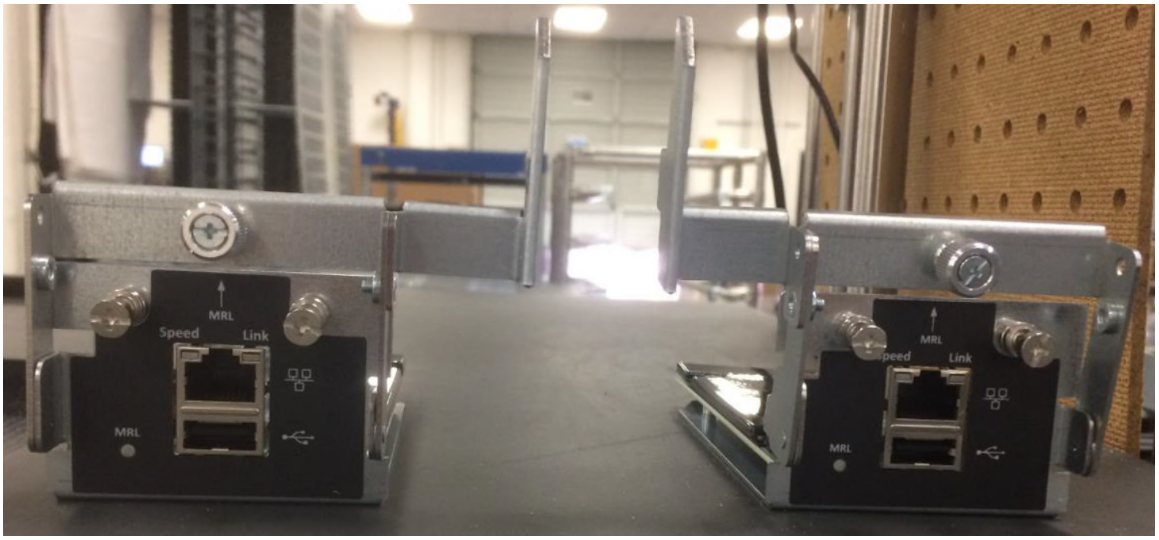
The regulatory label updates for 100SWD24B1N and 100SWD24CHS are shown in **Figure 3** and Error! Reference source not found. below.

Figure 3. 100SWD24 Regulatory Label, Before

Figure 4. 100SWD24 Regulatory Label, After

Change 3: The MRL bracket sheet metal on the SEEB assemblies has been updated with additional spacing to accommodate both 32-port (100SWDLF32Q) and 48-port (100SWDLF48D) leaf modules. Additional gasket material has also been added to the top and bottom of the midplanes to accommodate the thermal requirements of the 48-port leaf modules. A picture of the SEEB assemblies can be seen in **Figure 5** below.

Figure 5. 100SWD06 and 100SWD24 SEEB Assemblies



Before performing a full installation of 6 (for the 100SWD06 chassis) or 24 (for the 100SWD24 chassis) of the 48-port leaf modules, please ensure the Revision of the chassis is as indicated in the “Post Change MM# Rev” column of the Intel Ordering Code table found on Page 6. This label can be found at the bottom rear of the chassis next to the left SEEB assembly. An example of this label can be seen in **Figure 6** below.

Figure 6. Example of Product Revision indicator label on the 100SWD24B1N

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.
There is no change to the Intel Material Master (MM) numbers.
Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

* Other names and brands may be claimed as the property of others.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AA	Post Change AA
100SWD06B1N	945676	14	15	J12783-013	J12783-014	J11517-013	J11517-014
100SWD24B1N	945677	14	15	J12778-013	J12778-014	H89346-015	H89346-016
100SWDMGTSH	945776	07	08	H87892-009	H87892-010	H60416-012	H60416-013
100SWD06CHS	947192	07	08	J18616-006	J18616-007	J19700-004	J19700-005
100SWD24CHS	947193	07	08	J18618-006	J18618-007	J18617-004	J18617-005

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 13, 2018	00	Originally Published PCN

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